Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info	Subsectionals *	A-D
	Manufacturing Info		*** : Required Field**

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2014-04-28
Contact Name *	Refer to " Supplier Comment" section	Contact Title	Refer to " Supplier Comment" section
Contact Phone *	Refer to " Supplier Comment" section	Contact Email *	Refer to " Supplier Comment" section
Authorized Representative *	Giuseppe Vitali Palma	Representative Title	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to " Supplier Comment" section	Representative Email *	Refer to " Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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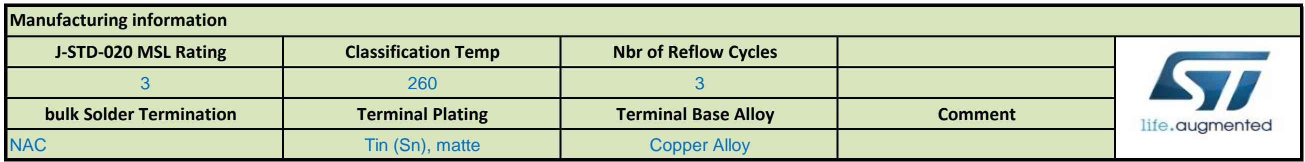
Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	CBO7*U1B6AB5	A	ZY1A	2014-04-28
	Amount	UoM	Unit type	ST ECOPACK Grade
	80.52	mg	Each	ECOPACK® 2



Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	4.85X3.9X1.52	8	gull wing	
Comment	Package: SO 08 .15 JEDEC ; MD valid also for SRK2000A			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	**Response**
Product(s) meets EU RoHS requirement without any exemptions	**true**
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false

Exemption Id.	**Description**

QueryList : REACH-16th December 2013	
Query	**Response**
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH	**true**

CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	CBO7*U1B6AB5					
Homogeneous Material	**Material Group**	**Mass**	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
SILICON DIE	Other inorganic materials	1.17	mg	supplier	DIE	Silicon (Si)	7440-21-3		1.13	mg	965812	14034
SILICON DIE				supplier	METALLIZATION	Aluminium (Al)	7429-90-5		0.009	mg	7692	112
SILICON DIE				supplier	METALLIZATION	Tungsten (W)	7440-33-7		0.007	mg	5983	87
SILICON DIE				supplier	PASSIVATION	Silicon Nitride (SiN)	68034-42-4		0.002	mg	1709	25
SILICON DIE				supplier	PASSIVATION	Silicon Oxide(SiO2)	7631-86-9		0.015	mg	12821	186
SILICON DIE				supplier	PASSIVATION	Gamma-butyrolactone	96-48-0		0.005	mg	4274	62
SILICON DIE				supplier	PASSIVATION	Polyhydroxyamide	55295-98-2		0.002	mg	1709	25
LEADFRAME	Copper and its alloy	26.787	mg	supplier	ALLOY	Copper (Cu)	7440-50-8		25.864	mg	965543	321212
LEADFRAME				supplier	ALLOY	Iron (Fe)	7439-89-6		0.623	mg	23258	7737
LEADFRAME				supplier	ALLOY	Zinc (Zn)	7440-66-6		0.032	mg	1195	397
LEADFRAME				supplier	ALLOY	Phosphorus (P)	7723-14-0		0.008	mg	299	99
LEADFRAME				supplier	COATING	Silver(Ag)	7440-22-4		0.26	mg	9706	3229
DIE ATTACH	Other organic materials	0.599	mg	supplier	GLUE	Epoxy resin A	9003-36-5		0.042	mg	70117	522
DIE ATTACH				supplier	GLUE	Epoxy resin B	68475-94-5		0.024	mg	40067	298
DIE ATTACH				supplier	GLUE	Silver(Ag)	7440-22-4		0.461	mg	769616	5725
DIE ATTACH				supplier	GLUE	Lactone	96-48-0		0.024	mg	40067	298
DIE ATTACH				supplier	GLUE	Polyoxypropylenediamine	9046-10-0		0.024	mg	40067	298
DIE ATTACH				supplier	GLUE	2,6-Diglycidyl phenyl allyl ether oligomer	EC 417-470-1		0.024	mg	40067	298
BONDING WIRE	Other inorganic materials	0.16	mg	supplier	BONDING WIRE	Gold (Au)	7440-57-5		0.16	mg	1000000	1987
ENCAPSULATION	Other organic materials	50.444	mg	supplier	MOLDING COMPOUND	Biphenyl epoxy resin	85954-11-6		3.747	mg	74280	46535
ENCAPSULATION				supplier	MOLDING COMPOUND	Silica fused (SiO2)	60676-86-0		42.969	mg	851816	533644
ENCAPSULATION				supplier	MOLDING COMPOUND	Phenol Resin	26834-02-6		1.999	mg	39628	24826
ENCAPSULATION				supplier	MOLDING COMPOUND	Carbon Black	1333-86-4		0.25	mg	4956	3105
ENCAPSULATION				supplier	MOLDING COMPOUND	Epoxy, Cresol Novolac	29690-82-2		0.999	mg	19804	12407
ENCAPSULATION				supplier	MOLDING COMPOUND	Bismuth (Bi)	7440-69-9		0.48	mg	9516	5961
FINISHING	Other inorganic materials	1.36	mg	supplier	CONNECTION COATING	Tin (Sn)	7440-31-5		1.36	mg	1000000	16890